

Contact Reactive Brazing of TC4 Alloy to Al7075 Alloy with Deposited Cu Interlayer

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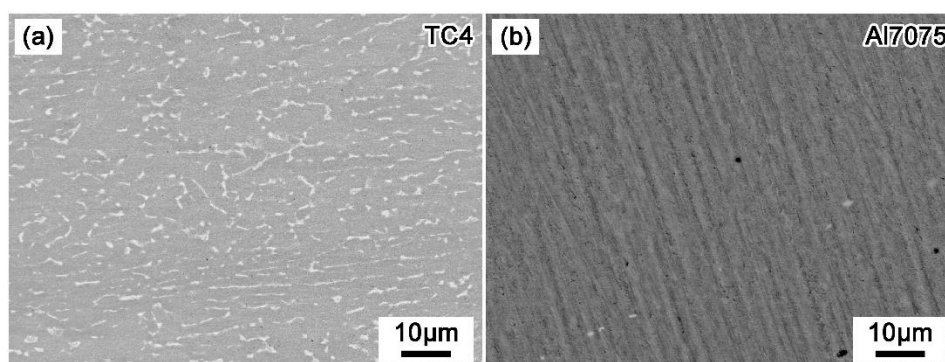


Figure S1. the characterization microstructures of the TC4 and Al7075 substrate: (a) TC4; (b) Al7075.

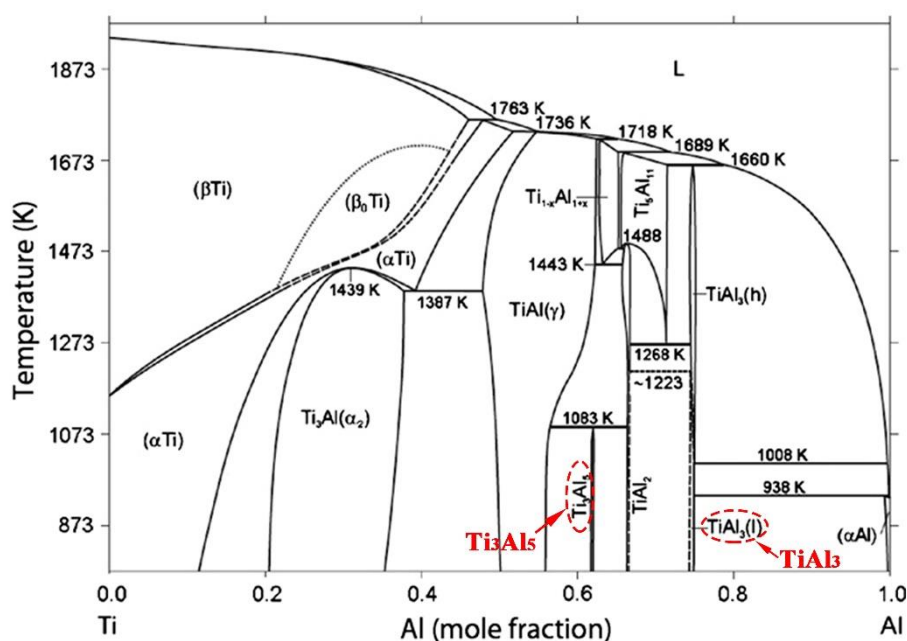


Figure S2. Al-Ti binary phase diagram.

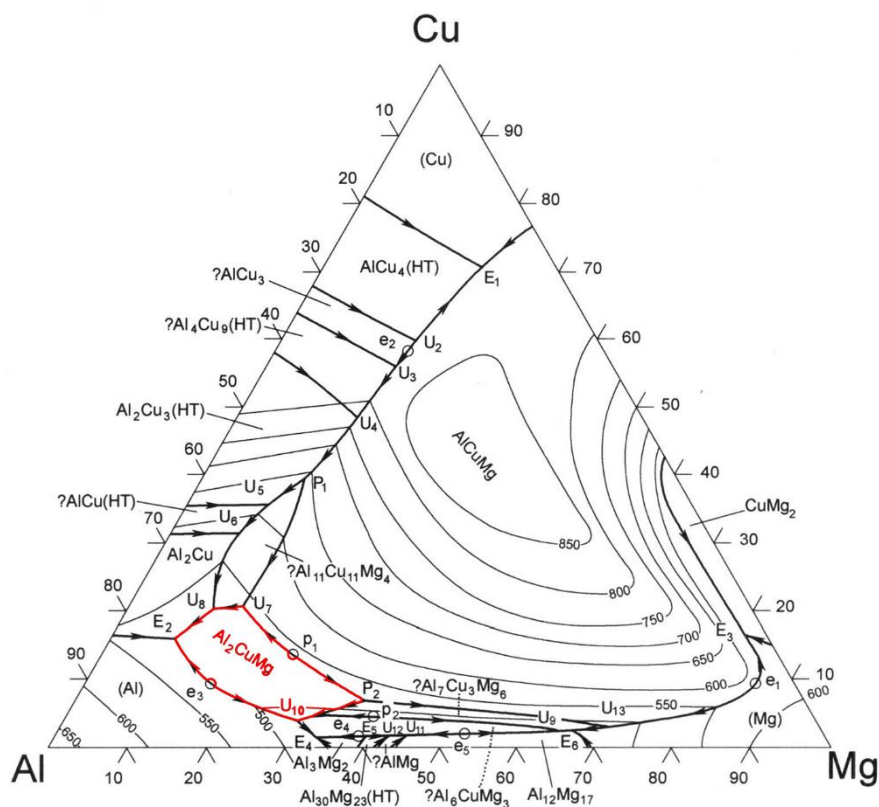


Figure S3. Al-Cu-Mg ternary phase diagram.

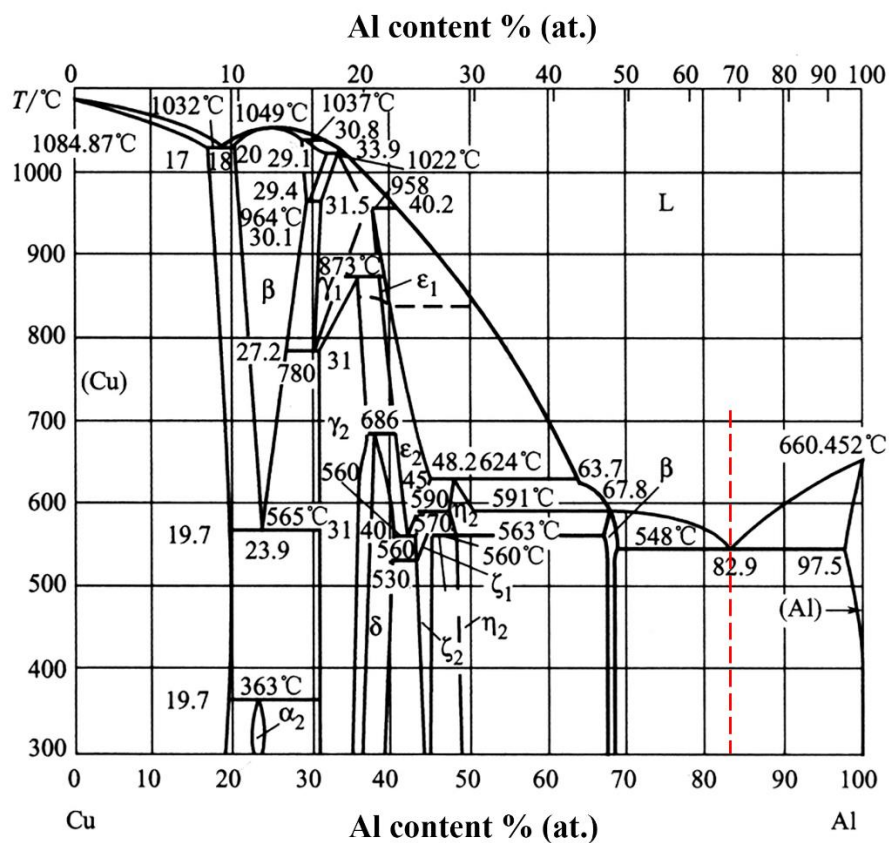


Figure S4. Al-Cu binary phase diagram.